

## CDIP / CerDIP

### Ceramic Dual-Inline Package (CDIP / CerDIP)

Amkor Technology is committed to continuing to service this long established standard industry package. The Amkor Technology CDIP capability provides a wide range of lead counts and body sizes. The CDIP is a hermetic package consisting of two pieces of dry pressed ceramic surrounding a "DIP formed" leadframe. The ceramic / LF / ceramic system is held together hermetically by frit glass reflowed at temperatures between 400° - 460° Centigrade.

### Applications:

Along with the other standard industry packages, the CDIP has a proven track record and is still being used by semiconductor technologies such as: Digital to Analog converters, EPROMS, Air bag sensors, Logic, Memory, Microcontrollers, and Video controllers. Some end applications are: Military electronics, Commercial electronics, Automotive and Telecommunications.

### Features:

The CDIP offers a variety of features:

- 300 mil package body width with lead counts from 8L to 28L
- 400 mil package body width with lead counts of 22L & 24L
- 600 mil package body width with lead counts from 24L to 40L
- 100 mil lead pitch
- High thermal conductive ceramic
- Matte Tin lead finish
- JEDEC standard compliant
- Wide selection of available cavity sizes to meet most die size needs
- Commercial or full Military flows

